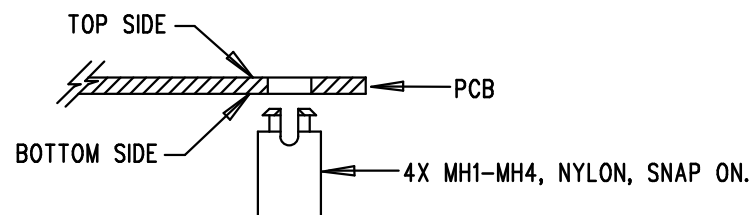
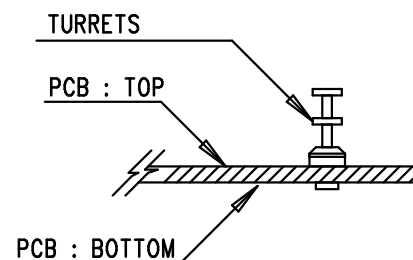
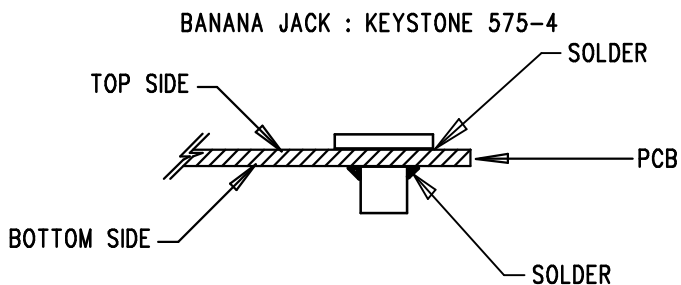


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL TURRETS AND STANDOFFS AS SHOWN BELOW:



8. INSTALL BANANA JACKS AS SHOWN BELOW:



TITLE: TOP ASSEMBLY DRAWING

60V LOW-IQ BOOST CONTROLLER

SIZE	IC NO.	REV.
N/A	LT8357JMSE EVAL-LT8357-AZ	1
		SHT 1 OF 1